

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
TETSUJI OHTA	04/07/2009
KEIKO KITAMURA	04/07/2009
MITSUHIRO WATANABE	04/09/2009

RECEIVING PARTY DATA

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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12525469

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NAME OF SUBMITTER:

GEORGE A. LOUD

Total Attachments: 2

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ASSIGNMENT

WHEREAS, I (we), Tetsuji OHTA, Keiko KITAMURA and Mitsuhiro WATANABE whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, is(are) the owner of certain new and useful improvements in Material for forming electroless plate, coating solution for adhering catalyst, method for forming electroless plate, and plating method (hereinafter referred to as the INVENTION) for which an application for United States Letters Patent was

executed on even date herewith

executed on:

filed on:

Serial No.:

established by PCT International Patent Application No.: PCT/JP2008 filed: February 1, 2008
designating the United States of America /051637

1) KIMOTO CO., LTD. of 19-1, Shinjuku 2-chome, Shinjuku-ku, Tokyo 160-0022, Japan
WHEREAS, 2) KANTO GAKUIN UNIVERSITY SURFACE ENGINEERING RESEARCH INSTITUTE of
~~XXXXXXXXXXXXXXXXXXXX~~ 4-1, Ikeda-cho 4-chome, Yokosuka-shi, Kanagawa 239-0806, Japan
hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United States;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application.

ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in connection with the filing, prosecution and maintenance of said application or any other patent application(s) in the United States for said INVENTION, including additional documents that may be required to affirm the rights of ASSIGNEE in and to said INVENTION, all without further consideration. ASSIGNOR also agrees, without further consideration and at ASSIGNEE'S expense, to identify and communicate to ASSIGNEE at ASSIGNEE'S request documents and information concerning the INVENTION that are within ASSIGNOR'S possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the prosecution, maintenance and defense of any patent application or patent encompassed within the terms of this instrument. ASSIGNOR'S obligations under this instrument shall extend to ASSIGNOR'S heirs, executors, administrators and other legal representatives.

ALSO, ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all Letters Patent referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title and interest in and to the same, for ASSIGNEE'S sole use and behoof; and for the use and behoof of ASSIGNEE'S legal representatives and successors, to the full end of the term for which such Letters Patent may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment and sale not been made.

ASSIGNOR authorizes any member of the firm of *Bacon & Thomas, PLLC* to insert or complete any information in this document needed to effect its recordal in the U.S. Patent and Trademark Office.

Assignor Name Tetsuji OHTA	Address c/o KIMOTO CO., LTD., 19-1, Shinjuku 2-chome, Shinjuku-ku, Tokyo 160-0022, Japan
Where Signed Tokyo Japan	
Date April 7 2009	Signature Tetsuji Ohta
Witness (optional)	Witness (optional)
Print/Type Name	Print/Type Name
Signature	Signature

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JOINT ASSIGNMENT - WITNESS

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<i>Witness (optional)</i>	<i>Witness (optional)</i>
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<i>Assignor Name</i> Mitsuhiro WATANABE	<i>Address</i> c/o KANTO GAKUIN UNIVERSITY SURFACE ENGINEERING RESEARCH INSTITUTE, 4-1, Ikeda-cho 4-chome, Yokosuka-shi, Kanagawa 239-0806, Japan
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<i>Signature</i>	<i>Signature</i>

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<i>Witness (optional)</i>	<i>Witness (optional)</i>
<i>Print/Type Name</i>	<i>Print/Type Name</i>
<i>Signature</i>	<i>Signature</i>

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